Film Capacitors

EMI suppression Film capacitors (MKP)

Series/Type: **B32021H/J ... B32026H/J**

Date: March 2024

Typical applications

- Y2 class for interference suppression
- "Line to ground" applications

Climatic

- Climatic category (IEC 60068-1:2013): 40/110/56

Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- AEC-Q200 compliant
- Small dimensions
- Good self-healing properties
- High voltage capability
- RoHS-compatible
- Halogen-free capacitors available on request

Terminals

- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

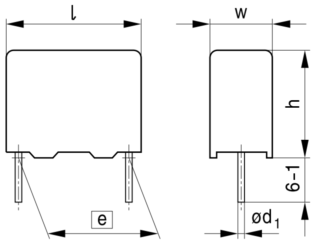
Marking

Manufacturer's logo, lot number,
date code, rated capacitance (coded),
capacitance tolerance (code letter),
rated AC voltage (IEC), series number,
sub-class (Y2), dielectric code (MKP),
climatic category, passive flammability category,
approvals

Delivery mode

- Bulk (untapped)
- Taped (Ammo pack or reel)
- For taping details, refer to chapter "Taping and packing"

Dimensional drawing



KMK0826-Q-E

Lead spacing (e±0.4)	Lead diameter d_1±0.05	Type
10	0.6	B32021H/J
15	0.8	B32022H/J
22.5	0.8	B32023H/J
27.5	0.8	B32024H/J
37.5	1.0	B32026H/J

Dimensions in mm

Marking example (position of marks may vary):

KMK2479-4

Approvals

Approval mark	Standard	Certificate
	EN 60384-14, IEC 60384-14	ENEC-04086 (approved by UL Demko)
	UL 60384-14, CSA E60384-14	E97863 (approved by UL)

Overview of available types

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
Type	B32021H/J	B32022H/J	B32023H/J	B32024H/J	B32026H/J
C_R (µF)					
0.0010					
0.0015					
0.0018					
0.0022					
0.0027					
0.0033					
0.0039					
0.0047					
0.0056					
0.0068					
0.0082					
0.010					
0.015					
0.018					
0.022					
0.027					
0.033					
0.039					
0.047					
0.056					
0.068					
0.082					
0.10					
0.15					
0.18					
0.22					
0.27					
0.33					
0.39					
0.47					
0.56					
0.68					
0.82					
1.0					

Ordering codes and packing units

Lead spacing mm	C_R µF	Max. dimensions w x h x l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ
10	0.0010	4.0 x 9.0 x 13.0	B32021H3102+***	4000	6800	4000
	0.0015	4.0 x 9.0 x 13.0	B32021H3152+***	4000	6800	4000
	0.0018	4.0 x 9.0 x 13.0	B32021H3182+***	4000	6800	4000
	0.0022	4.0 x 9.0 x 13.0	B32021H3222+***	4000	6800	4000
	0.0027	4.0 x 9.0 x 13.0	B32021H3272+***	4000	6800	4000
	0.0033	4.0 x 9.0 x 13.0	B32021H3332+***	4000	6800	4000
	0.0039	5.0 x 11.0 x 13.0	B32021J3392+***	3320	5200	4000
	0.0047	5.0 x 11.0 x 13.0	B32021H3472+***	3320	5200	4000
	0.0056	5.0 x 11.0 x 13.0	B32021H3562+***	3320	5200	4000
	0.0068	5.0 x 11.0 x 13.0	B32021H3682+***	3320	5200	4000
	0.0082	6.0 x 12.0 x 13.0	B32021H3822+***	2720	4400	4000
	0.010	6.0 x 12.0 x 13.0	B32021H3103M***	2720	4400	4000
15	0.010	5.0 x 10.5 x 18.0	B32022H3103+***	4680	5200	4000
	0.015	6.0 x 11.0 x 18.0	B32022H3153+***	3840	4400	4000
	0.018	6.0 x 12.0 x 18.0	B32022H3183+***	3840	4400	4000
	0.022	6.0 x 12.0 x 18.0	B32022H3223M***	3840	4400	4000
	0.022	7.0 x 12.5 x 18.0	B32022J3223+***	3320	3600	4000
	0.027	7.0 x 12.5 x 18.0	B32022H3273+***	3320	3600	4000
	0.033	8.0 x 14.0 x 18.0	B32022H3333+***	2920	3000	2000
	0.039	8.0 x 14.0 x 18.0	B32022H3393M***	2920	3000	2000
	0.039	8.5 x 14.5 x 18.0	B32022J3393+***	2720	2800	2000
	0.047	8.5 x 14.5 x 18.0	B32022H3473M***	2720	2800	2000
	0.047	9.0 x 17.5 x 18.0	B32022J3473+***	2560	2800	2000
	0.056	9.0 x 17.5 x 18.0	B32022H3563+***	2560	2800	2000
	0.068	9.0 x 17.5 x 18.0	B32022H3683M***	2560	2800	2000
	0.068	11.0 x 18.5 x 18.0	B32022J3683+***	–	2200	1200
	0.082	11.0 x 18.5 x 18.0	B32022H3823M***	–	2200	1200

MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further intermediate capacitance values on request.

Composition of ordering code

\+ = Capacitance tolerance code:
K = ±10%
M = ±20%

*** = Packaging code:
289 = Straight terminals, Ammo pack
189 = Straight terminals, Reel
003 = Straight terminals, untaped (lead length 3.2 ±0.3 mm)
004 = Straight terminals, untaped (lead length 4.0 ±0.3 mm)
000 = Straight terminals, untaped (lead length 6 –1 mm)

Lead spacing mm	C_R µF	Max. dimensions w x h x l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ
22.5	0.047	6.0 x 15.0 x 26.5	B32023H3473+***	2720	2800	2880
	0.056	6.0 x 15.0 x 26.5	B32023H3563M***	2720	2800	2880
	0.068	7.0 x 16.0 x 26.5	B32023H3683+***	2320	2400	2520
	0.068	7.5 x 14.5 x 26.5	B32023J3683M***	2200	2000	2280
	0.082	8.5 x 16.5 x 26.5	B32023H3823+***	1920	2000	2040
	0.10	8.5 x 16.5 x 26.5	B32023H3104M***	1920	2000	2040
	0.10	10.5 x 16.5 x 26.5	B32023J3104+***	1560	1600	2160
	0.15	10.5 x 18.5 x 26.5	B32023H3154M***	1560	1600	2160
	0.15	10.5 x 20.5 x 26.5	B32023J3154+***	-	1600	2160
	0.18	11.0 x 20.5 x 26.5	B32023H3184M***	-	1400	2040
	0.22	12.0 x 22.0 x 26.5	B32023H3224M***	-	1200	1800
	0.22	14.5 x 29.5 x 26.5	B32023J3224+***	-	–	1040
	0.27	14.5 x 29.5 x 26.5	B32023H3274+***	-	–	1040
	0.33	14.5 x 29.5 x 26.5	B32023H3334+***	-	–	1040
	0.39	14.5 x 29.5 x 26.5	B32023H3394M***	-	–	1040
27.5	0.15	11.0 x 19.0 x 31.5	B32024H3154+***	–	1400	1280
	0.18	11.0 x 19.0 x 31.5	B32024H3184+***	–	1400	1280
	0.22	11.0 x 19.0 x 31.5	B32024H3224M***	–	1400	1280
	0.22	11.0 x 21.0 x 31.5	B32024J3224+***	–	1400	1280
	0.27	12.5 x 21.5 x 31.5	B32024H3274+***	–	1200	1120
	0.33	13.5 x 23.0 x 31.5	B32024H3334M***	–	1000	1040
	0.33	14.0 x 24.5 x 31.5	B32024J3334+***	–	1000	1040
	0.39	15.0 x 24.5 x 31.5	B32024H3394+***	–	1000	960
	0.47	15.0 x 24.5 x 31.5	B32024H3474M***	–	1000	960
	0.47	16.0 x 32.0 x 31.5	B32024J3474+***	–	–	880
	0.56	16.0 x 32.0 x 31.5	B32024H3564+***	–	–	880
	0.68	18.0 x 33.0 x 31.5	B32024H3684+***	–	–	800
	0.68	21.0 x 31.0 x 31.5	B32024J3684+***	–	–	720
	0.82	22.0 x 36.5 x 31.5	B32024H3824+***	–	–	640
	1.0	22.0 x 36.5 x 31.5	B32024H3105+***	–	–	640

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000 = Straight terminals, untaped (lead length 6 –1 mm)

Lead spacing mm	C_R µF	Max. dimensions w x h x l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ
37.5	0.33	12.0 x 22.0 x 42.0	B32026H3334+***	–	–	1620
	0.39	12.0 x 22.0 x 42.0	B32026H3394+***	–	–	1620
	0.47	14.0 x 25.0 x 42.0	B32026H3474+***	–	–	1380
	0.56	14.0 x 25.0 x 42.0	B32026H3564M***	–	–	1380
	0.56	16.0 x 28.5 x 42.0	B32026J3564+***	–	–	800
	0.68	16.0 x 28.5 x 42.0	B32026H3684+***	–	–	800
	0.82	16.0 x 28.5 x 42.0	B32026H3824M***	–	–	800
	0.82	18.0 x 32.5 x 42.0	B32026J3824+***	–	–	720
	1.0	18.0 x 32.5 x 42.0	B32026H3105M***	–	–	720
	1.0	20.0 x 39.5 x 42.0	B32026J3105+***	–	–	640

MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further intermediate capacitance values on request.

Composition of ordering code

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M = ±20%

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289 = Straight terminals, Ammo pack
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000 = Straight terminals, untaped (lead length 6 –1 mm)

Ordering code example

B	**3202**	**4**	**H**	**3**	**105**	**M**
Components class	Series	Lead space (mm)	Dimensions code	Rated voltage	Rated capacitance	Capacitance tolerance
Passive components	MKP	1 = 10 2 = 15 3 = 22.5 4 = 27.5 6 = 37.5	See table "Ordering codes and packing units"	3 = 300 V AC	105 = 1000 nF = 1.0 µF	K = ±10% M = ±20% + = K or M

Technical data

Reference standard: UL / IEC 60384-14:2013 / AMD1:2016. All data given at T = 20°C, unless otherwise specified.

Rated AC voltage V_R	300 V AC (50/60 Hz)	
Maximum continuous DC voltage V_{DC}	1500 V DC	
Rated temperature T_R (UL / IEC60384-14:2013 / AMD1:2016)	+110 ºC	
Min. category temperature T_{min}	–40 ºC	
Max. operating temperature $T_{op,max} = T_{amb} + T_{self\text{-}heating}$	+125 °C Note: At T >110 ºC derating for V_R or V_{DC} should be 1.5%/ºC. Duration time ≤1000 h.	
DC test voltage between terminals	4000 V, 2 s (C_R ≤0.33 µF) 3700 V, 2 s (C_R >0.33 µF)	
Configurations with several capacitors in parallel and additional DC test repetition during a longer time period (3700 or 4000 V DC @ 60 s depending on capacitance value) require customized solutions which are available upon request.		
Dissipation factor tan δ (in 10^{-3}) at 20 °C (upper limit values)	1.0 at 1kHz	
Insulation resistance R_{ins} or time constant $\tau = C_R \cdot R_{ins}$ at 100 V DC, 20 °C, rel. humidity ≤65% and for 60 s (minimum as-delivered values)	C_R ≤0.33 µF 15 000 MΩ	C_R >0.33 µF 5 000 s
Passive flammability category	B	
Capacitance tolerances (measured at 1 kHz)	±10% (K), ±20% (M)	
Biased humidity test	Test conditions Temperature: +40 °C ±2 °C Relative humidity: 93% RH ±2% Voltage value: V_R or V_{DC} Test duration: 1000 h	
Limit values after damp heat test	Capacitance change (ΔC/C): ≤ ±10% Dissipation factor change (Δtan δ): ≤15 x 10^{-3} (at 1 kHz) Insulation resistance R_{ins}: ≥50% of initial limit	

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/µs.

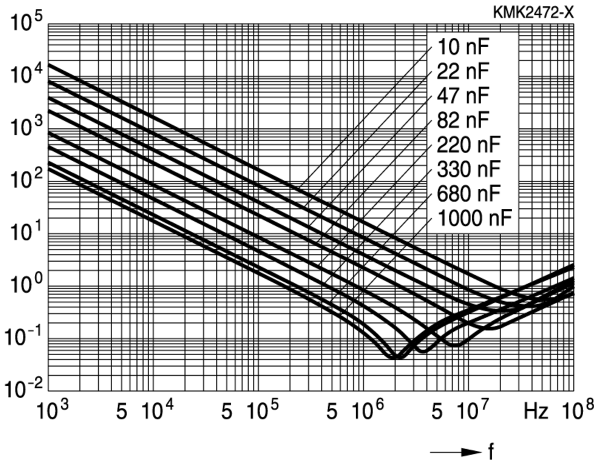
"k_0" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V^2/µs.

Note:
The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor. These parameters are given for isolated pulses in such a way that the heat generated by one pulse will be completely dissipated before applying the next pulse. For a train of pulses, please refer to the curves of permissible AC voltage-current versus frequency.

dV/dt and k0 values

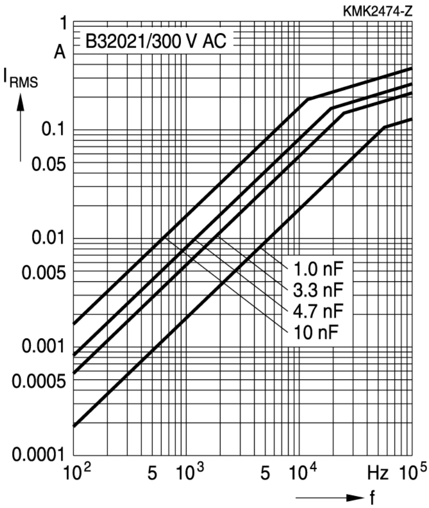
Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
dV/dt in V/µs	800	600	500	400	300
k_0 in V^2/µs	667 000	508 000	423 000	338 000	254 000

Impedance Z versus frequency f
(typical values)

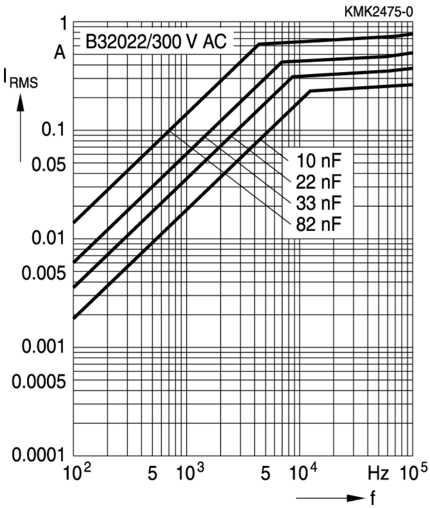


Permissible AC current IRMS versus frequency f (for sinusoidal waveforms T_A ≤100 ºC and ∆ESR <100% from receipt condition)

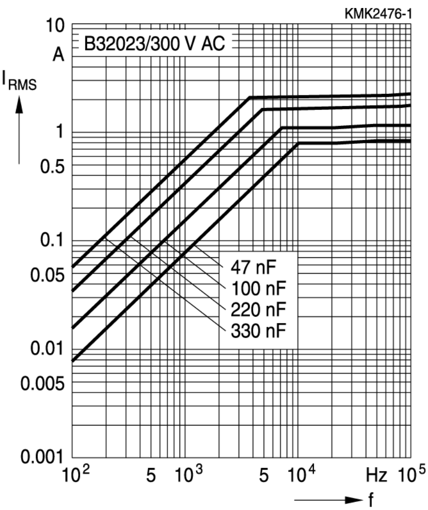
Lead spacing 10 mm



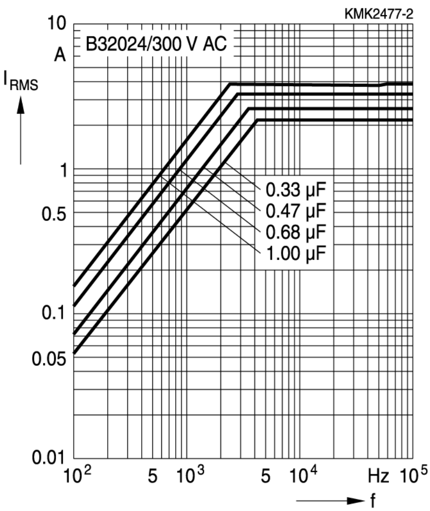
Lead spacing 15 mm



Lead spacing 22.5 mm

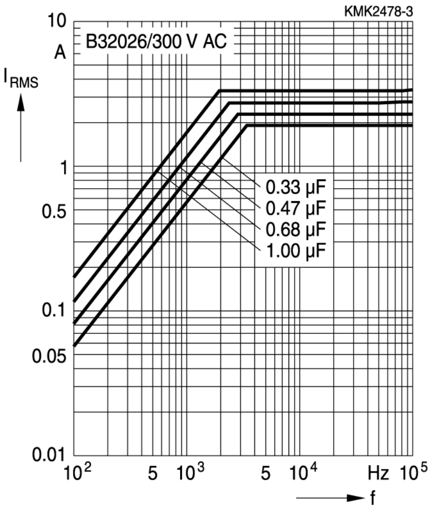


Lead spacing 27.5 mm



Permissible AC current IRMS versus frequency f (for sinusoidal waveforms T_A ≤100 ºC and ∆ESR <100% from receipt condition)

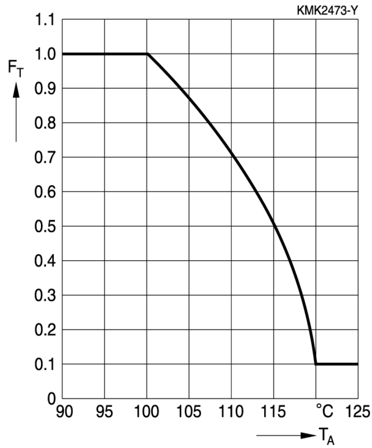
Lead spacing 37.5 mm



Maximum current I_{RMS} vs. temperature T_A>100ºC

The graphs described in the previous section for the maximum current vs. frequency are valid for moderate temperature: $T_A \leq 100$ °C in MKP. For temperatures higher than these limits, we have to consider additional effects depending on the frequency and dielectric:

- Low frequency (f >f1)
  For frequency below f1 (The frequency is the I_{RMS} begin to derating vs. frequency), a derating of the I_{RMS} versus the working temperature has to be applied, following the rules defined above (derating 1.5%/ºC).
- High frequencies (f1 ≤f)
  For frequency below f1 (The frequency is the I_{RMS} begin to derating vs. frequency), a derating of the I_{RMS} versus the working temperature has to be applied, following the rules defined as below:

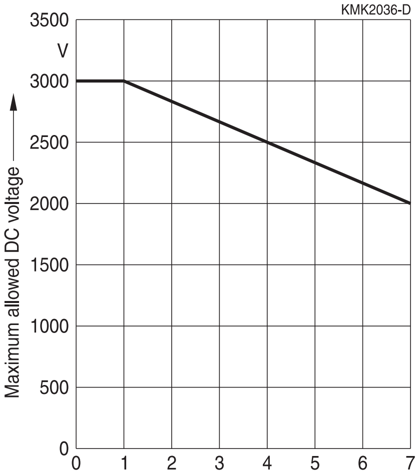


Derating factor F_T for I_{RMS} vs. T_A

Parallel configuration

Only capacitors of the same capacitance may be connected in parallel and the maximum DC test voltage must be reduced as a function of the total parallel capacitance value. The diagram below shows a typical trend of maximum allowed voltage versus total parallel capacitance. (Cut off current 10 mA, rise time ≤1000 V/s, dwell time ≤2 s, maximum allowed parallel connected capacitors 8 pcs.).

B3202* DC test voltage as function of total parallel capacitance (µF):



Total parallel capacitance (µF)

Testing and standards

<table>
<tr><th>Test</th><th>Reference</th><th>Test conditions</th><th>Performance requirements</th></tr>
<tr><td>Electricity parameters</td><td>IEC 60384-14: 2013 /AMD1: 2016</td><td>Voltage proof between terminals: 1500 V AC, 1 min;
Terminals and enclosure:
2 V_R + 1500 V AC;
Insulation resistance R_{INS}
Capacitance C_R
Dissipation factor tan δ</td><td>Within specified specification</td></tr>
<tr><td>Robustness of terminations</td><td>IEC 60068-2-21: 2006</td><td>Tensile strength (test U_a1)<table><tr><td>Wire diameter</td><td>Tensile force</td></tr><tr><td>0.5 <d1 ≤0.8mm
0.8 <d1 ≤1.25mm</td><td>10 N
20 N</td></tr></table></td><td>Capacitance and tan δ within specified limits</td></tr>
<tr><td>Resistance to soldering heat</td><td>IEC 60068-220:2008
Test Tb
Method 1A</td><td>Solder bath temperature at 260 ±5 °C, immersion for 10 s</td><td>$\Delta C/C0 \leq 5\%$
tan δ within specified limits</td></tr>
<tr><td>Vibration</td><td>IEC 60384-14: 2013 /AMD1: 2016</td><td>Test FC: vibration sinusoidal
Displacement: 0.75 mm
Acceleration: 98 m/s^2
Frequency: 10 Hz ... 500 Hz
Test duration:
orthogonal axes, 2 h each axe</td><td>No visible damage</td></tr>
<tr><td>Bump</td><td>IEC 60384-14:2013 /AMD1: 2016</td><td>Test Eb: Total 4000 bumps with 400 m/s^2 mounted on PCB, 6 ms duration</td><td>No visible damage
$|\Delta C/C0| \leq 5\%$
tan δ within specified limits</td></tr>
<tr><td>Damp heat, steady state</td><td>IEC 60384-14: 2013 /AMD1: 2016</td><td>40 °C / 93% relative humidity / 56 days</td><td>No visible damage
$|\Delta C/C0| \leq 5\%$
$|\delta$ tan$| \leq 0.008$ at 1 kHz
Voltage proof
$R_{INS} \geq 50\%$ of initial limit</td></tr>
<tr><td>Rapid change of temperature</td><td>IEC 60384-14: 2013 /AMD1: 2016</td><td>T_A = lower category temperature
T_B = upper category temperature
5 cycles, duration t = 30 min</td><td>No visible damage
$|\Delta C/C0| \leq 5\%$
tan δ within specified limits</td></tr>
</table>

Test	Reference	Test conditions	Performance requirements
Climatic sequence	IEC 60384-14: 2013 /AMD1: 2016	Dry heat: T_B / 16 h. Damp heat cyclic, 1st cycle +55 °C / 24 h / 95% ... 100% RH Cold : T_A / 2 h Damp heat cyclic, 5 cycles +55 °C / 24 h / 95% ... 100% RH	No visible damage $\|\Delta C/C0\| \leq 5\%$ $\|\delta \tan\| \leq 0.008$ at 1 kHz Voltage proof $R_{INS} \geq 50\%$ of initial limit
Impulse test endurance	IEC 60384-14: 2013 /AMD1: 2016	T_B / 1.7 V_R / 1000 h, 1000 V_{RMS} for 0.1 s every hour	No visible damage $\|\Delta C/C0\| \leq 10\%$ $\|\delta \tan\| \leq 0.008$ at 1 kHz Voltage proof $R_{INS} \geq 50\%$ of initial limit
Passive flammability	IEC 60384-14:2013 /AMD1:2016	Flame applied for a period of time depending on capacitor volume	B
Active flammability	IEC 60384-14: 2013 /AMD1: 2016	20 discharges at 5 kV + V_R	The cheesecloth shall not burn with a flame.
Biased humidity test	AEC-Q200D	40°C / 93%relative humidity / V_R / 1000 h	No visible damage $\|\Delta C/C0\| \leq 10\%$ $\|\delta \tan\| \leq 0.015$ at 1 kHz $R_{INS} \geq 50\%$ of initial limit
Temperature cycling	AEC-Q200D	T_A= lower category temperature T_B = upper category temperature 1000 cycles, duration t = 30 min	No visible damage $\|\Delta C/C0\| \leq 5\%$

Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20:2008, test Ta, method 1.

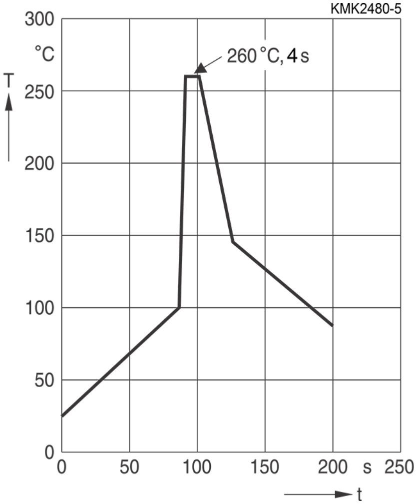
Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2:2007, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/–0.5 mm from capacitor body or seating plane
Evaluation criteria: Visual inspection	 Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20:2008, test Tb, method 1. Conditions:

Series		Solder bath temperature	Soldering time
MKT	boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing >10 mm)	260 ±5 °C	10 ±1 s
MFP MKP	 (lead spacing >7.5 mm)		
MKT	boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP MKT	(lead spacing ≤7.5 mm) uncoated (lead spacing ≤10 mm) insulated (B32559)		<4 s recommended soldering profile for MKT uncoated (lead spacing ≤10 mm) and insulated (B32559)



Immersion depth	2.0 +0/–0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification

1.3 General notes on soldering

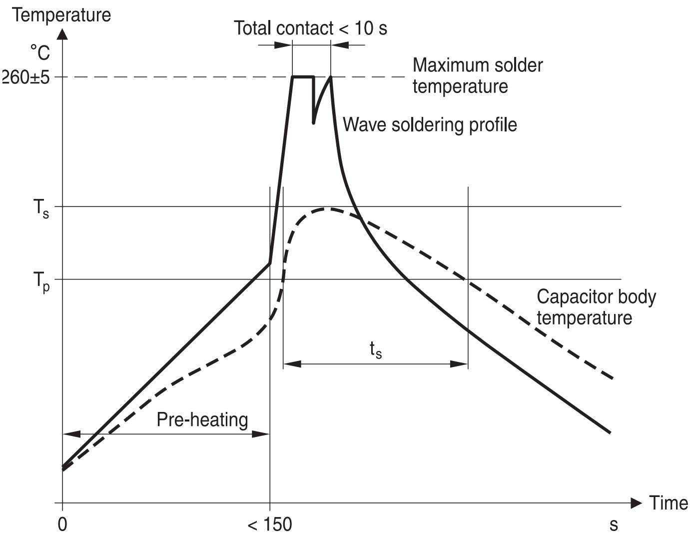
Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max}. Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
  diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

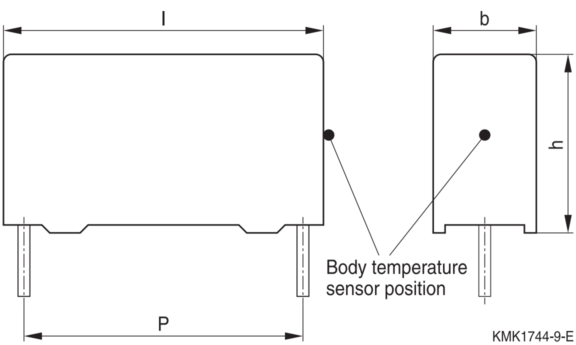
Recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



T_s: Capacitor body maximum temperature at wave soldering
T_p: Capacitor body maximum temperature at pre-heating

KMK1745-A-E



KMK1744-9-E

Body temperature should follow the description below:

- MKP capacitor
  During pre-heating: $T_p \leq 110$ °C
  During soldering: $T_s \leq 120$ °C, $t_s \leq 45$ s
- MKT capacitor
  During pre-heating: $T_p \leq 125$ °C
  During soldering: $T_s \leq 160$ °C, $t_s \leq 45$ s

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor (T_s) must be ≤120 °C.

One recommended condition for manual soldering is that the tip of the soldering iron should be <360 °C and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

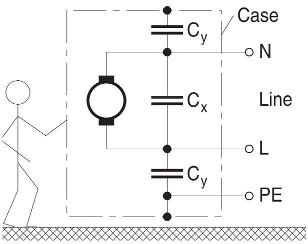
Please refer to our Film Capacitors Data Book in case more details are needed.

Application note

A Y capacitor to be connected between AC lines and the Frame Ground (FG) has an effect of emitting common mode current to the FG.Leak current corresponding in frequency and voltage to the AC power supply flows in the Y capacitor.

As the capacity of a Y capacitor grows, leak current also increases. This can cause electric shock. Therefore, UL and other safety standards restrict the capacity so that the amount of leak current does not exceed a certain level. Usually, two Y capacitors are used, as shown in figure below. As AC lines are connected with capacitors; they are effective in reducing differential mode noises. In particular, they are effective for high frequency ranges of 8 to 10 MHz.

Example of EMI suppression, typical application:



Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.
- Consult us if application is with severe temperature and humidity condition.
- There are no serviceable or repairable parts inside the capacitor. Opening the capacitor or any attempts to open or repair the capacitor will void the warranty and liability of TDK Electronics.
- Please note that the standards referred to in this publication may have been revised in the meantime.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6:2007. TDK Electronics offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

Design of our capacitors

Our EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC 60384-14:2013 (4^{th} edition) / UL 60384-14:2014 (2^{nd} edition) must be performed at 1.25 × V_R at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC 60384-14:2013 (4^{th} edition) / UL 60384-14:2014 (2^{nd} edition) establishes high voltage tests performed at 4.3 × V_R – 1 minute, impulse testing at 2500 V for C = 1 µF and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value.
For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.
Detailed information can be found on the Internet under www.tdk-electronics.tdk.com/orderingcodes.

Correlation of data sheet values and modelling tool outputs

Data sheet values and results of design tools may deviate as they have not been derived in the same context.

While data sheets show individual parameter statements without considering a possible dependency to other parameters. Tools model a complete given scenario as input and processed inside the tool.

Furthermore as we constantly strive to improve our models, the results of tools can change over time and be a non-binding indication only.

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_C	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
β_C	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f_1	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f_2	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f_r	Resonant frequency	Resonanzfrequenz
F_D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I_C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)
I_{RMS}	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
i_z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
L_S	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_0	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase

Symbol	English	German
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
R_i	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_S	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
T	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
tan δ_D	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_S	Series component of dissipation factor	Serienanteil des Verlustfaktors
T_A	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
T_{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t_{OL}	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
T_{op}	Operating temperature, $T_A + \Delta T$	Beriebstemperatur, $T_A + \Delta T$
T_R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t_{SL}	Reference service life	Referenz-Lebensdauer
V_{AC}	AC voltage	Wechselspannung
V_C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_i	Input voltage	Eingangsspannung
V_o	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub

Symbol	English	German
V_R	Rated voltage	Nennspannung
$\hat{V}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
$\boxed{e}$	Lead spacing	Rastermaß

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.

2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.

3. **The warnings, cautions and product-specific notes must be observed**.

4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.tdk-electronics.tdk.com/material). Should you have any more detailed questions, please contact our sales offices.

5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order.
   We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available. The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

6. Unless otherwise agreed in individual contracts, **all orders are subject to our General Terms and Conditions of Supply**.

Important notes

7. **Our manufacturing sites serving the automotive business apply the IATF 16949 standard**. The IATF certifications confirm our compliance with requirements regarding the quality management system in the automotive industry. Referring to customer requirements and customer specific requirements ("CSR") TDK always has and will continue to have the policy of respecting individual agreements. Even if IATF 16949 may appear to support the acceptance of unilateral requirements, we hereby like to emphasize that **only requirements mutually agreed upon can and will be implemented in our Quality Management System**. For clarification purposes we like to point out that obligations from IATF 16949 shall only become legally binding if individually agreed upon.
8. The trade names EPCOS, CarXield, CeraCharge, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CTVS, DeltaCap, DigiSiMic, FilterCap, FormFit, InsuGate, LeaXield, MediPlas, MiniBlue, MiniCell, MKD, MKK, ModCap, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PiezoBrush, PlasmaBrush, PowerHap, PQSine, PQvar, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, SurfIND, ThermoFuse, WindCap, XieldCap are **trademarks registered or pending** in Europe and in other countries. Further information will be found on the Internet at www.tdk-electronics.tdk.com/trademarks.

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